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Smart Dustbin Monitoring System Using IOT

F. Yuthiskumar, Dr P. Santhanalakshmi

II MCA Students, Department of Master of Computer Applications, Hindusthan College of Engineering and Technology,
Coimbatore, India

Assistant Professor, Department of Master of Computer Applications, Hindusthan College of Engineering and
Technology, Coimbatore, India

ABSTRACT: The Smart Dustbin project integrates essential components such as an ultrasonic sensor, LCD display, Node MCU, and Internet of Things (IoT) connectivity to offer a cutting-edge technical solution to improve waste management techniques. Getting acquainted with your new surroundings. The dustbin's fill level is precisely measured by the ultrasonic sensor, providing trustworthy data for efficient garbage collection. As a local interface, the LCD display informs users in real time on the condition of the trash can. Waste management authorities can use this information to make data-driven decisions about how best to schedule efficient pickups, optimize collection routes, and cut operational expenses.

KEYWORDS: Electrical, Internet Of Things, Dustbin, Monitor, ultrasonic

I. INTRODUCTION

The Smart Dustbin project integrates essential components such as an ultrasonic sensor, LCD display, Node MCU, and Internet of Things (IoT) connectivity to offer a cutting-edge technical solution to update waste management procedures. This cutting-edge technology seeks to improve productivity, encourage environmental sustainability, and offer real-time trash disposal process monitoring and control. An ultrasonic sensor for accurate fill level monitoring, an LCD display for local status indication, a Node MCU for microcontroller capability, and IOT connectivity for smooth communication with a centralized server or cloud platform are the essential parts of the Smart Dustbin.



Figure 1 illustrates the block diagram of the Internet of Things.

LCD Display : Display the level of dustbin
Ultrasonic : Detect the level of waste in the dustbin
NodeMCU : Used to send the notification through the internet

The dustbin's fill level is precisely measured by the ultrasonic sensor, providing trustworthy data for efficient garbage collection. The LCD display functions as a local interface, giving customers feedback in real time about the dustbin's present condition. The central processing unit, or Node MCU, facilitates communication and data processing between the IoT platform and the trash.

II. HOW IT WORKS

An essential component of urban infrastructure is garbage management, and as cities become smarter and more sustainable, creative solutions are needed to solve the problems with conventional waste disposal techniques. The Smart Dustbin project, which integrates essential parts such as an ultrasonic sensor, LCD display, NodeMCU, and Internet of Things (IoT) connectivity, represents a technical leap in waste management. By redefining the effectiveness and responsiveness of trash disposal procedures, this integrated system hopes to create smarter, more ecologically conscious cities. • The introduction of a dynamic, real-time waste bin monitoring system is the main goal of the Smart Dustbin project. Scheduled pickups are the foundation of traditional garbage management, which frequently leads to either overfilled bins or needless collections. This initiative aims to lower operating costs, improve garbage collection procedures, and create a more sustainable urban environment by incorporating cutting-edge technologies.

In addition to providing users with information, this local display makes maintenance and troubleshooting simple. The NodeMCU functions as the Smart Dustbin's brain, facilitating communication with the IoT platform and connecting the LCD display and ultrasonic sensor. Based on the ESP8266 Wi-Fi module, NodeMCU is an open-source Internet of Things platform that offers the computing capacity and network connectivity required to send data to the cloud, enabling smooth communication and integration with more extensive waste management systems. One of the main components of the Smart Dustbin project is the integration of IoT. Real-time data transmission to a cloud platform or centralized server is made possible by this link.

III. SYSTEM OVERVIEW

By continuously checking the dustbin's fill level, you can increase the effectiveness of waste collecting. Minimize fuel use, cut down on pointless garbage collection trips, and improve the routing of waste management trucks. Reduce the operating expenses related to the management and collection of garbage. By planning collections and routes based on actual fill levels, you may reduce fuel, labour, and maintenance costs. Reduce the carbon emissions from needless rubbish collection journeys to help the environment stay sustainable. When the trashcan is almost full, notify the waste management authorities or staff to help avoid overflow and pollution. Public areas become cleaner as a result of this. To find the distance to the trash, connect the ultrasonic sensor to the microcontroller. This will assist in estimating the amount of garbage. To determine whether the bin is full or requires care, write code to read the sensor data. Provide reasoning for any extra features you add, like trash compaction. Connect the Bluetooth or Wi-Fi module to the microcontroller so that it can communicate. By doing this, the trashcan can transmit data to a linked device or a central server. Configure cloud connectivity if you wish to save data or receive notifications from a distance.

Data on the fill level, weight, presence of gas, and ambient variables are gathered via sensors. This data is processed by the microcontroller. The waste management team receives notifications and alerts when appropriate actions need to be taken. ensures dustbins are emptied only when necessary, cutting down on pointless journeys. detects and notifies users of potentially dangerous situations

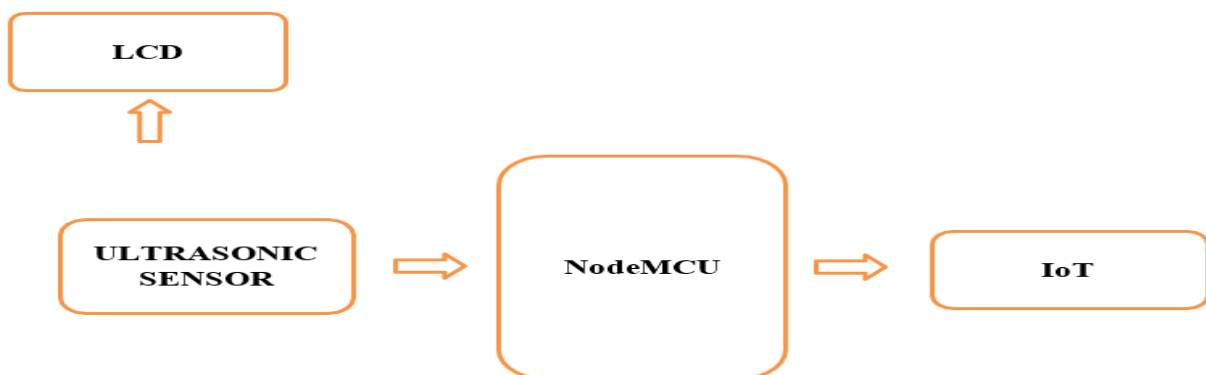


Figure 2: System Block Diagram

IV. HARDWARE DECERPTION

NODE MCU

NodeMCU is the system's microcontroller unit; it is built around the ESP8266 Wi-Fi module. It analyzes the information obtained from the ultrasonic sensor and makes it easier for the sensor, LCD display, and Internet of Things platform to communicate with one another. By establishing a connection with the nearby Wi-Fi network, NodeMCU facilitates easy integration with the larger IoT infrastructure. The NodeMCU's computational capacity guarantees effective data processing and the smart algorithms' implementation for waste management optimization.

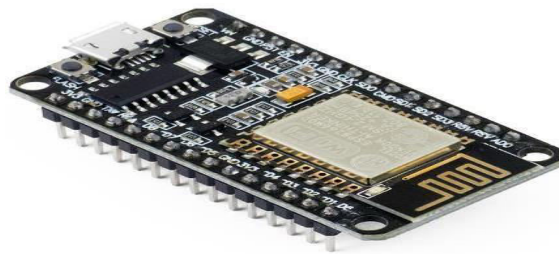


Figure 3 : Node MCU

Lua scripting: When NodeMCU first came out, it offered a scripting environment based on Lua, which let programmers use the Lua language to write code directly on the module. Because of this, people who were unfamiliar with embedded programming could understand it.

WiFi Connectivity: Enabling WiFi connectivity for Internet of Things (IoT) applications is the primary goal of the NodeMCU firmware. The module has internet-based communication capabilities and can establish connections with nearby WiFi networks.

Arduino Compatibility: Although the NodeMCU firmware was initially developed using Lua, there are ESP8266 firmware variants that are compatible with Arduino. This enables programmers to use the Arduino IDE, a well-liked development environment for embedded projects, to program the module.

GPIO Pins: You may communicate with external components like sensors, actuators, LEDs, and more using the General Purpose Input/ Output (GPIO) pins on the ESP8266 module.

Integrated Development Environment (IDE): A variety of IDEs, including the Arduino IDE and the NodeMCU-specific IDE, can be used to develop NodeMCU applications. Code authoring, code compilation, and code uploading facilities are included in these IDEs.

Community and Documentation: The active and thriving NodeMCU community offers users assistance, documentation, and tutorials. As a result, introducing new users to the technology is made simpler.

Rapid Development and Prototyping: Because of their affordability and user-friendliness, NodeMCU and ESP8266 are well-liked options for IoT project development and prototyping.

PIN DESCRIPTION

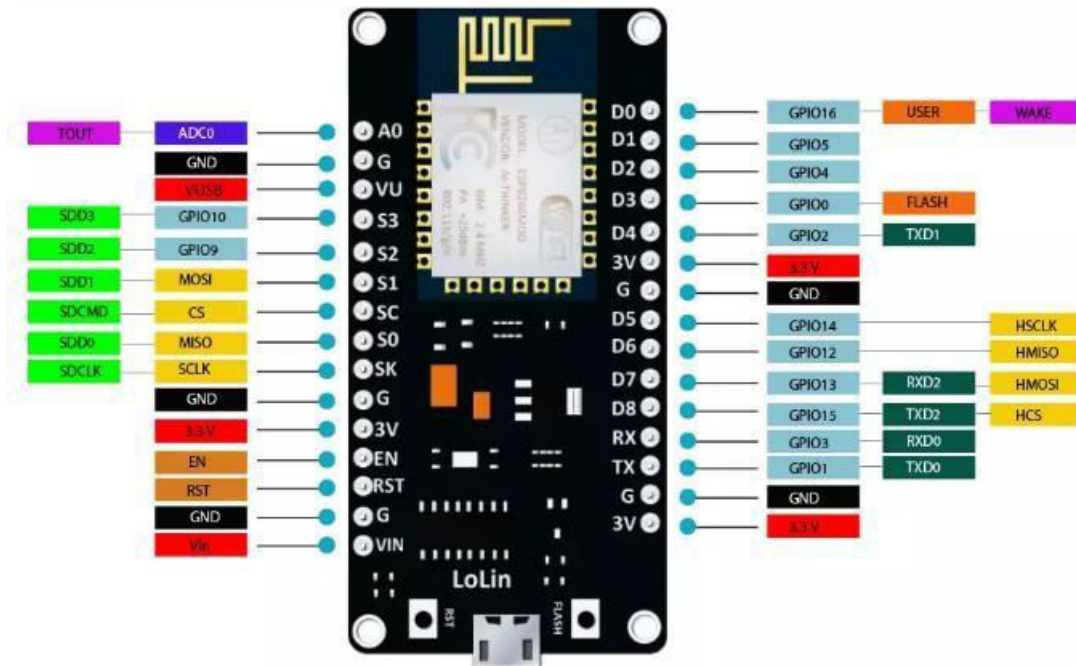


Figure 4.1: Pin Description

3V3 (3.3V): Provides an external component with a regulated 3.3V power source. This voltage level is the operating voltage for several parts of the board.

RST (Reset): This feature lets you restart your application or reset the module to force an ESP8266 reset.

GND (Ground): Offers the circuit's common ground reference. Attach the ground connections of the components here.

D0 (GPIO16): A digital I/O pin with general purpose that can be used for input or output. able to rouse the ESP8266 from a sound slumber.

D1 (GPIO5, SCL): Connects sensors and devices using I2C, a two-wire serial communication interface. It acts as the clock (SCL) pin.

D2 (GPIO4, SDA): Serves as I2C communication's data (SDA) pin, enabling data transfer between devices. D2 (GPIO4, SDA): Serves as I2C communication's data (SDA) pin, enabling data transfer between devices.

D3 (GPIO0): Digital I/O pin with general purpose. It affects the ESP8266's boot mode during boot-up.

General-purpose digital I/O pin D4 (GPIO2). has an impact on boot mode as well as boot-up.

D5 (GPIO14, SCLK): A clock (SCLK) pin that synchronizes data flow between devices via SPI connection. PWM is also supported.

General-purpose digital I/O pin D8 (GPIO15). It can be used as an input or an output and supports PWM. TX (GPIO1): Data can be transmitted from the board to other devices using UART serial connectivity.

RX (GPIO3): Receive pin used for data reception from other devices via UART serial communication.

Analog input pin A0 (ADC): Used to read analog voltages with the Analog to Digital Converter (ADC). helpful for interpreting the output from analog sensors.

Vin: Pin used to input voltage from an external power source. External power is applied to the board, usually at

5V. EN (Enable): This button turns on or off the ESP8266 module.

LED display

One popular kind of alphanumeric display module that can show two lines of text with a maximum of 16 characters per line is a 16x2 LCD (Liquid Crystal Display). These screens are frequently used to show information to people in a variety of electronics projects, gadgets, and applications. The following information relates to a standard 16x2 LCD module:

Display Size: There are two lines on the LCD screen, and a maximum of 16 characters (letters, numbers, symbols, and spaces) can be shown on each line.

Character Size: A wide range of characters and symbols can be displayed thanks to the standard character size of 5 by 8 pixels.

Backlight: To enhance visibility in varying lighting conditions, a backlight that can be adjusted is a feature of many 16x2 LCD modules. White, blue, green, or other colors can be used for the backlight.

Communication Interface: Hitachi HD44780 or a similar controller, which is often interfaced with microcontrollers via a parallel interface, is used by 16x2 LCD modules.

PIN DESCRIPTION

VSS (Ground): Attach to your power supply's ground.

VDD (Power): Attach to the voltage of the positive supply, which is typically +5V.

V0 (Contrast): This pin regulates the display's contrast. To change the contrast, connect to a fixed resistor divider or a variable resistor.

RS (Register Select) : alternates between the data mode (RS = 1) and the command mode (RS = 0). The module gets character data while it is in data mode. It takes commands to adjust the display settings when it is in command mode.

RW (Read/Write): The read (RW = 1) or write (RW = 0) mode is selected by this pin. This pin is typically connected to ground (write mode) since the majority of applications only need to write data to the LCD.

SPECIFICATION

Display Size	16 characters x 2 lines.
Character Size	5x8 pixels (5 pixels wide, 8 pixels high).
Controller	HD44780
Operating Voltage	5V
Interface:	4-bit or 8-bit / I2C/SPI
Viewing Area	2.95mm x 5.55mm
Contrast Control	potentiometer or resistor to V0
Temperature Range	0°C to 50°C
Dimensions	80mm x 36mm x 12mm (W x H x D)

ULTRASONIC SENSOR

Ultrasonic sensors are extensively employed in a wide range of applications, including level sensing, obstacle avoidance, object detection, and distance measuring. They function by releasing ultrasonic waves and timing how long it takes for the waves to return to the sensor after bouncing off an object. The speed of sound in air can be used to compute the distance to the item based on this time delay.



Figure 4.2: Ultrasonic sensor

PIN DESCRIPTION

VCC (Power Supply, +5V): This pin supplies the sensor with its operating voltage, usually +5V. Attach it to your power supply's positive terminal.

Trig (Trigger, Input): The ultrasonic measurement is started by the Trigger pin, which is an input pin. You must deliver a brief pulse to this pin—at least 10 microseconds—in order to begin a measurement. After obtaining this pulse, the sensor releases an ultrasonic pulse.

Echo (Output): An output pin that gives a pulse with a duration equal to the ultrasonic pulse's travel time to and from the object is called the Echo pin. The distance between the sensor and the item determines how long this pulse is. GND stands for ground. To finish the circuit, connect this pin to your power supply's ground (0V).

Operating Voltage	5V DC
Operating Current	15mA
Operating Frequency	40KHz
Min Range	2cm / 1 inch
Max Range	400cm / 13 feet
Accuracy	3mm
Measuring Angle	<15°
Dimension	45 x 20 x 15mm

WORKING

High-frequency sound waves, usually in the ultrasonic range (above human audible range), provide the basis for the operation of an ultrasonic sensor. These sensors are frequently employed in navigation, object detection, and distance measuring applications.

Ultrasonic Wave Emission: The transmitter and receiver make up the ultrasonic sensor. Short bursts of ultrasonic waves sound waves with a frequency greater than what the human ear can detect—are released by the transmitter. Like audible sound waves, these waves travel through the air as a sequence of compressions and rarefactions.

Reflection from Objects: Because of the difference in air density between the object and the generated ultrasonic waves, these waves reflect back when they come into contact with surfaces or objects along their route. The waves return to the

sensor after bouncing off the item.

SYSTEM FLOW

- The WiFi connection is initialized by NodeMCU.
- The configured WiFi network is connected to by NodeMCU.
- There is confirmation of a successful Wi-Fi network connection.
- An ultrasonic sensor gauges the dustbin's fill level.
- Analyze the smart dustbin's ability to recognize and react to variations in fill level. Check the system's response time when the trash can is filled or emptied.
- Make that user data is safeguarded and that IoT connectivity is secure. Put authentication and encryption procedures in place to stop unwanted

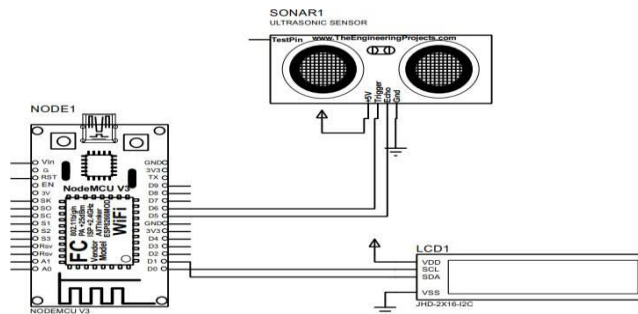


Figure 5.1 Circuit diagram

V. RESULT AND DISCUSSION

Analyze the smart dustbin's ability to recognize and react to variations in fill level. When the garbage is full or emptied, note how quickly the system responds. Evaluate how the mobile application feels to use. Check the accuracy of the information sent to the IoT platform by the ultrasonic sensor. Find any differences between the reported data and the actual fill level. To make sure the system is sustainable and energy-efficient, measure the total power consumption. Examine the system's general dependability throughout a prolonged duration. Evaluate the smart dustbin's performance under various environmental circumstances. Make that user data is safeguarded and that IoT connectivity is secure. Put authentication and encryption procedures in place to stop unwanted

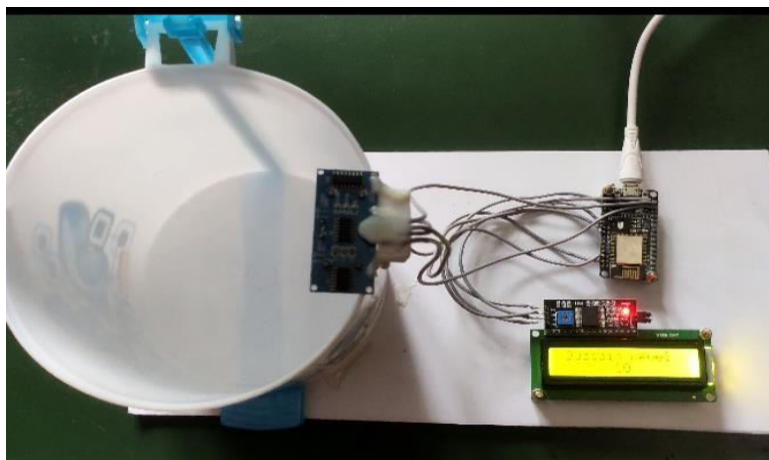


Figure 5.1 Dustbin level

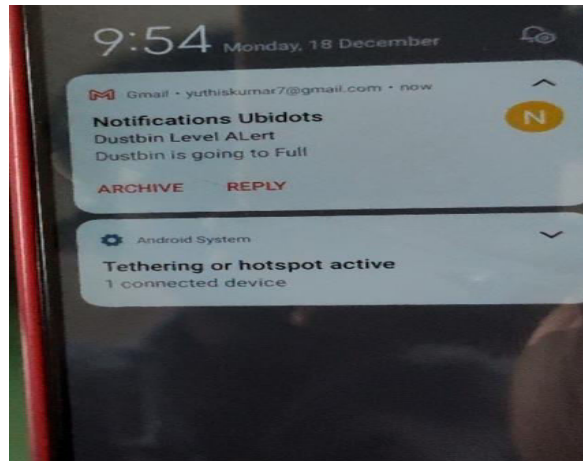


Figure 5.2 Alert Message

VI. CONCLUSION

By enabling prompt and efficient waste disposal through real-time fill level monitoring, the smart dustbin greatly increases waste collection efficiency. By enabling remote control functionality, the mobile application improves user comfort by enabling users to operate the dustbin without needing to contact physically. The gathered information provides insightful information about usage trends, which aids in streamlining resource allocation, waste collection schedules, and overall waste management tactics.

The smart dustbin helps cut down on fuel use and greenhouse gas emissions from pointless collection trips by optimizing rubbish collection routes based on fill levels. The ability to successfully integrate IoT technology shows that adding intelligent solutions to conventional infrastructure for enhanced functionality is feasible. This smart dustbin monitoring system, which makes use of NodeMCU and IoT technology, is an excellent example of how creative solutions can revolutionize established procedures. It demonstrates how IoT may enhance urban management and provides a globally replicable and adaptable solution for improved trash management and environmental sustainability.

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